

FDH055N15A N-Channel PowerTrench[®] MOSFET **150 V, 167 A, 5.9 m**Ω

Features

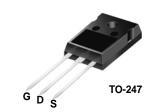
- $R_{DS(on)}$ = 4.8 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 120 A
- Fast Switching Speed
- · Low Gate Charge
- High Performance Trench Technology for Extremely Low R_{DS(on)}
- High Power and Current Handling Capability
- · RoHS Compliant

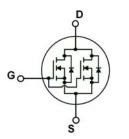
Description

This N-Channel MOSFET is produced using Fairchild ${\sf Semiconductor}^{@}{\sf 's}$ advance ${\sf PowerTrench}^{@}$ process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		FDH055N15A	Unit		
V _{DSS}	Drain to Source Voltage			150	V		
V _{GSS}	Gate to Source Voltage			±20	V		
I _D	Drain Current	- Continuous (T _C = 25°C, Silicon	Limited)	167*			
		- Continuous (T _C = 100 ^o C, Silico	n Limited)	118	A		
		- Continuous (Tc = 25°C, Packag	ge Limited)	156	1		
I _{DM}	Drain Current	- Pulsed	(Note 1)	668	А		
E _{AS}	Single Pulsed Avalanche	(Note 2,5)	835	mJ			
dv/dt	Peak Diode Recovery dv/c	it	(Note 3)	6.0	V/ns		
P _D	David Diasia dias	$(T_{\rm C} = 25^{\rm o}{\rm C})$		429	W		
	Power Dissipation	- Derate above 25°C		2.86	W/ºC		
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C		
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C		

mum allowable junction temperature, Package limit

Thermal Characteristics

Symbol	Parameter	FDH055N15A	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.35	
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink, Typical	0.24	°C/W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient, Max.	40	

March 2013

Device Ma	Device Marking Device Pac		Packa	ge	Reel Size	Таре	e Width		Quantit	у
FDH055N			TO-24	17	-		-		30	
Electrica	Char	acteristics T _c =	25°C unless	s otherwi	se noted					
Symbol		Parameter		Test Conditions		Min.	Тур.	Max.	Unit	
Off Charac	teristic	S								
BV _{DSS}	Drain to	to Source Breakdown Voltage		I _D = 2	50μA, V _{GS} = 0V		150	-	-	V
ΔBV _{DSS} ΔTJ	Breakd Coeffici	akdown Voltage Temperature		$I_D = 250\mu A$, Referenced to $25^{\circ}C$			-	0.1	-	V/ºC
	Zoro C	Zana Osta Malla na Davia Osmanl		$V_{DS} = 120V, V_{GS} = 0V$ $V_{DS} = 120V, T_C = 150^{\circ}C$		-	-	1	μA	
IDSS	Zero Gate Voltage Drain Current		201			-	-	500		
I _{GSS}	Gate to Body Leakage Current		t	$V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±100	nA	
On Charac	teristic	s								
V _{GS(th)}		hreshold Voltage		V _{GS} = V _{DS} , I _D = 250μA			2.0	-	4.0	V
R _{DS(on)}	Static D	Prain to Source On Res	istance	$V_{GS} = 10V, I_D = 120A$			-	4.8	5.9	mΩ
9 _{FS}	Forwar	Forward Transconductance		$V_{DS} = 10V, I_{D} = 120A$			-	219	-	S
Dynamic C	haracte	eristics								
C _{iss}	T	t Capacitance				-	7100	9445	pF	
C _{oss}		Capacitance		$V_{DS} = 75V, V_{GS} = 0V$ = 1MHz		-	664	885	pF	
C _{rss}	Reverse	e Transfer Capacitance	;			-	23	35	pF	
C _{oss(er)}	Energy	Related Output Capac	citance	V _{DS} =	75V, V _{GS} = 0V		-	1159	-	pF
Q _{g(tot)}	Total Ga	ate Charge at 10V					-	92	-	nC
Q _{gs}	Gate to	Source Gate Charge		$V_{DS} = 75V, I_D = 120A$ $V_{GS} = 10V$ (Note 4)		-	-	31	-	nC
Q _{gs2}	Gate Cl	harge Threshold to Pla	teau			-	15	-	nC	
Q _{gd}	Gate to	Drain "Miller" Charge				-	16	-	nC	
ESR	Equival	ent Series Resistance(G-S)	f= 1M	Hz		-	1.2	-	Ω
Switching	Charac	teristics								
t _{d(on)}	Turn-Or	n Delay Time		$V_{DD} = 75V, I_D = 120A$ $V_{GS} = 10V, R_{GEN} = 4.7\Omega$			-	35	80	ns
t _r	Turn-Or	n Rise Time				-	67	144	ns	
t _{d(off)}	Turn-Of	f Delay Time				-	71	152	ns	
t _f	Turn-Of	f Fall Time				(Note 4)	-	21	52	ns
Drain-Sour	ce Dio	de Characteristic	s							
I _S	Maximum Continuous Drain to Source Dio			ode Forward Current		-	-	167*	Α	
I _{SM}	Maximum Pulsed Drain to Source Diode F		Forward Current		-	-	668	Α		
V _{SD}	Drain to	Source Diode Forward	J Voltage	$V_{GS} =$	0V, I _{SD} = 120A		-	-	1.25	V
t _{rr}	Reverse	e Recovery Time		$V_{GS} = 0V, I_{SD} = 120A, V_{DS} = 75V$		= 75V	-	105	-	ns
Q _{rr}	Reverse	e Recovery Charge			= 100A/µs	F	-	342	-	nC
Q _{rr}	Reverse	Reverse Recovery Charge		$V_{GS} = 0V, I_{SD} = 30A, V_{DS} = 75V$ dI _F /dt = 100A/µs			-	348	-	nC

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2. Starting $T_J = 25^{\circ}$ C, L = 3 mH, $I_{AS} = 23.6$ A.

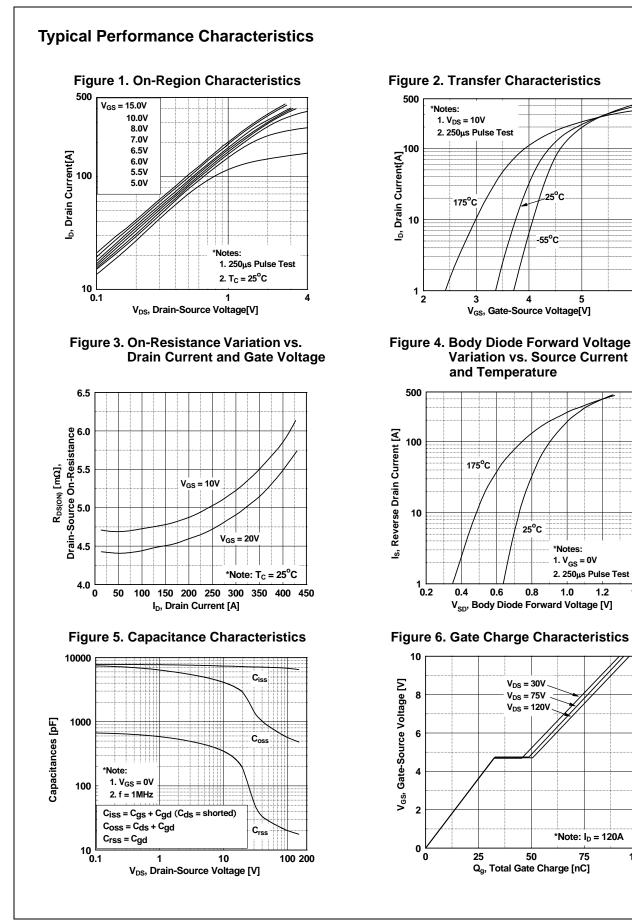
3. I_{SD} \leq 120A, di/dt \leq 200A/µs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C.

4. Essentially Independent of Operating Temperature Typical Characteristics.

5. Single Pulsed Avalanche Energy per Die.

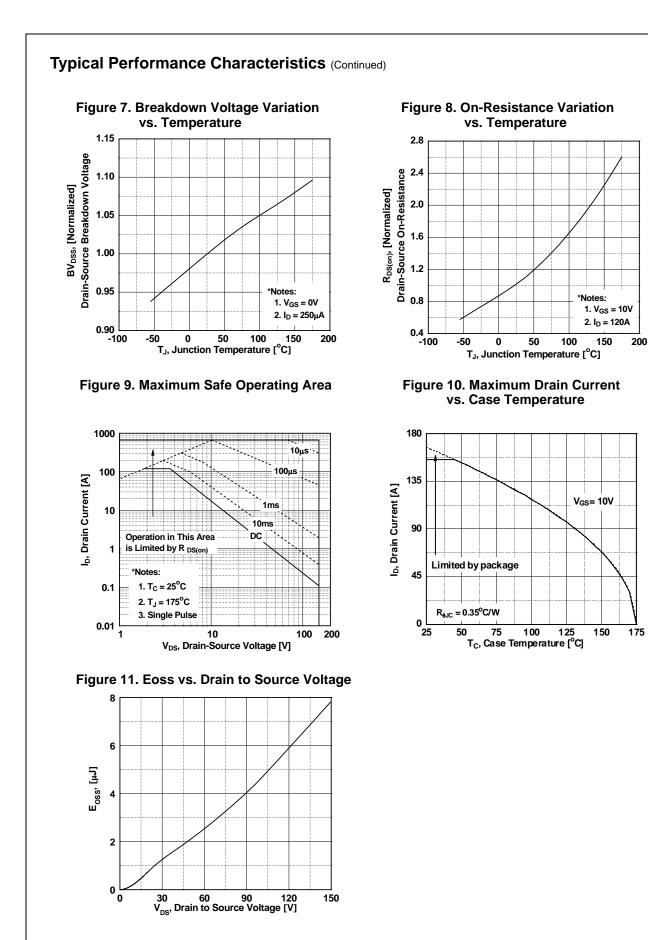
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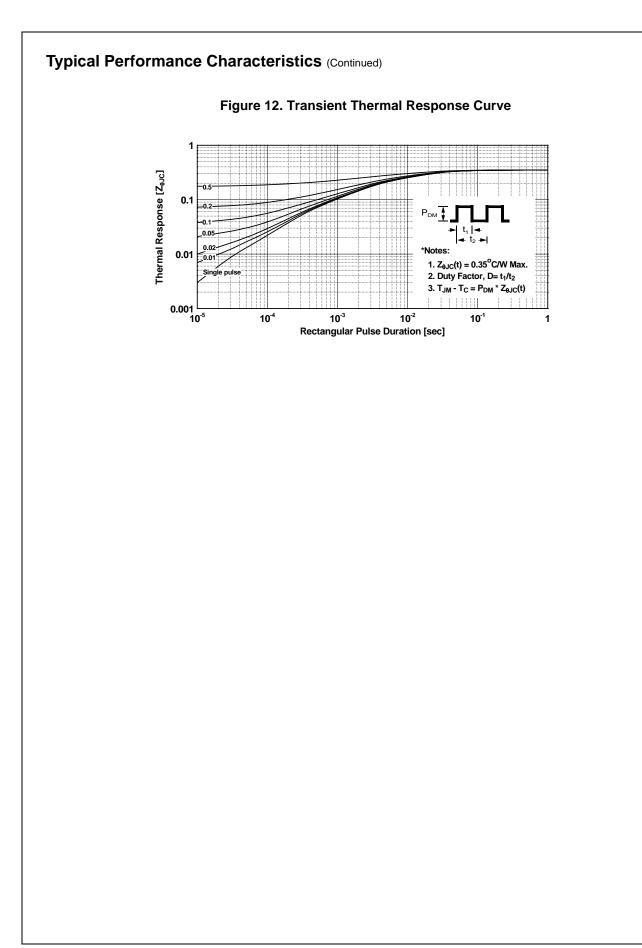
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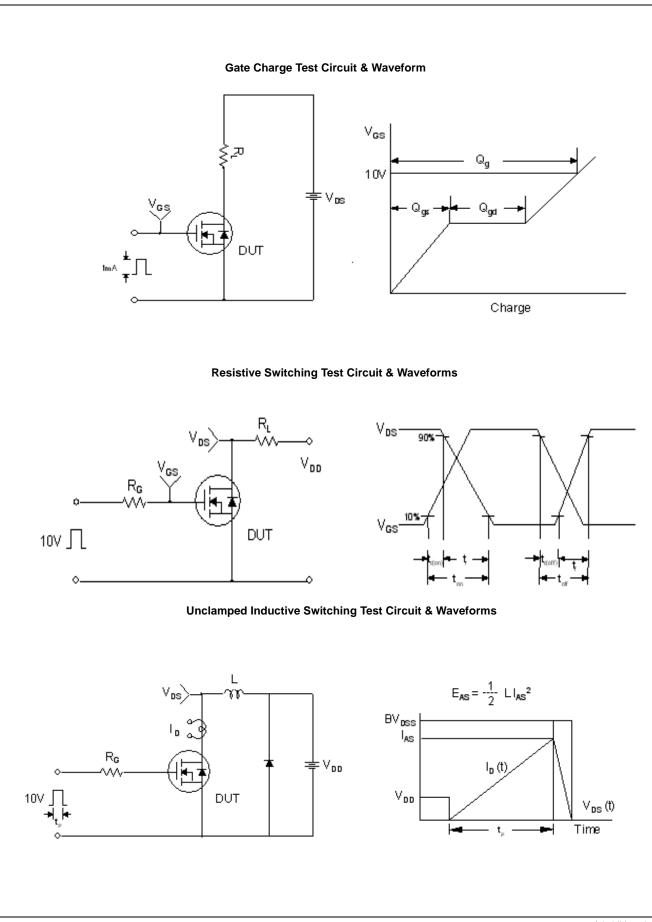


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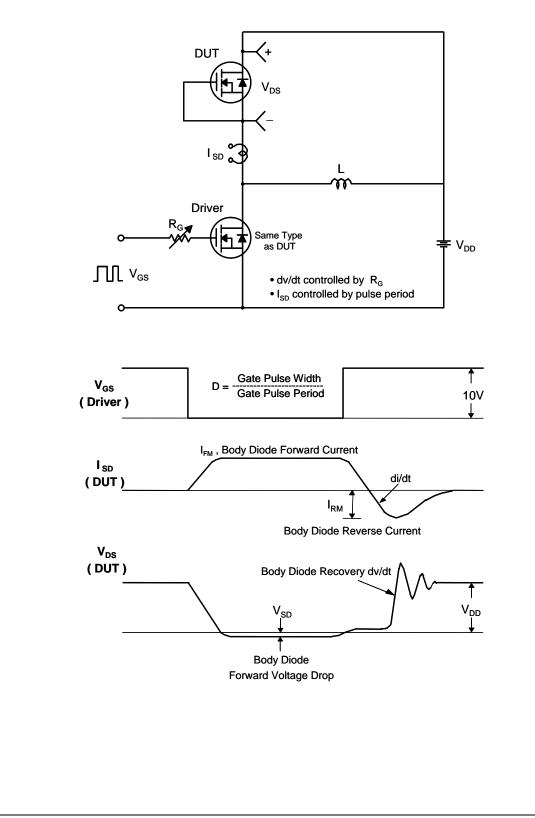


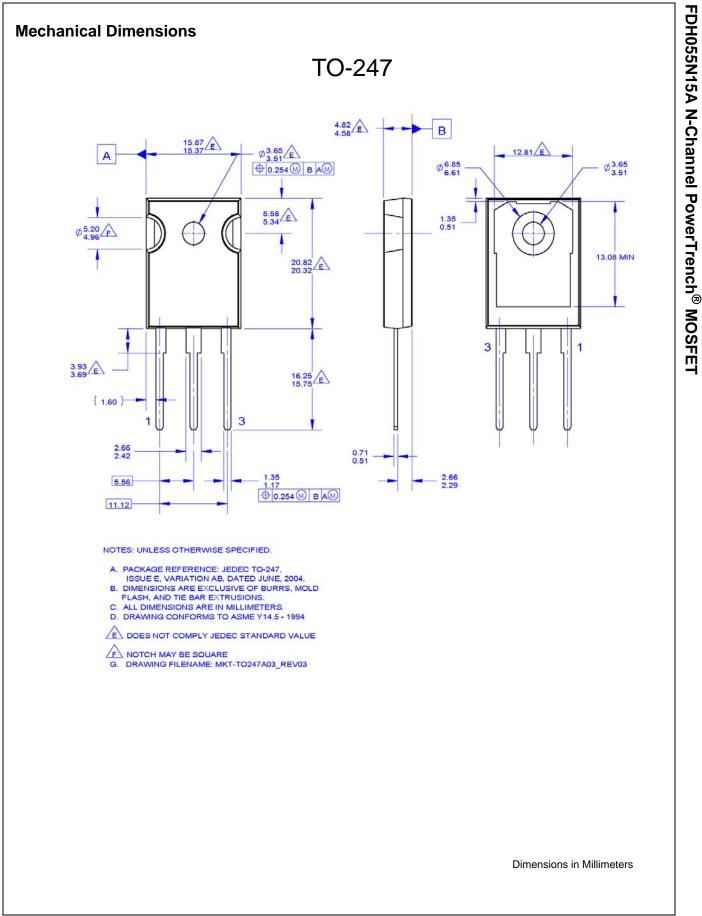




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